



# NATIONAL PRODUCTS

COMMITTED TO QUALITY

AN ISO 9001:2015 & 14001:2015 CERTIFIED COMPANY



## About NP Solders

**National Products (NP)** commenced its operation in the year 1987 with an aim to manufacture the range of quality and High Performance Solders, Fluxes & Solvents, SMT Solder Paste and PCB Chemicals used in electronics, instrumentation, automobiles, telecommunication, computer and other allied industries. The company with its administrative office located in New Delhi and manufacturing plant in Neemrana ,Rajasthan initiated its operation with the manufacturing of Fluxes, Solvents and subsequently added Solder Stick/Ingot, Solder Wire, Solder Paste and environment friendly lead free Solder & Paste to its range of products.

The National Products is comprised of highly professional team of R&D, technical, commercial and management for day to day support and its customer satisfaction for his entire product range.

# Why National Products?

We offer the quality array of products which includes **High-performance Solders, Fluxes & Solvents, SMT Solder Paste and PCB Chemicals** used in electronics, instrumentation, automobiles, telecommunication, computer and other allied industries.

Furthermore, due to the following attributes, our organization has been able to attain a distinguished position in the market:

- **Industry leading prices**
- **Extensive product portfolio to choose from**
- **Superior range of products**
- **Customized products**
- **On time delivery**
- **Excellent packaging to avoid damage**
- **State-of-the-art infrastructure**
- **Total quality & customer satisfaction**
- **Consistent Product Performance**
- **Regionally consistent technical support to customers**

**“Our Technician Are Available To Interact and Develop Any Other Formulation to Meet Clients Specific Requirements”**

# Certifications



Scan this QR Code with smartphone to verify the certificate

## CERTIFICATE OF REGISTRATION

This is to certify that the Environmental Management System of:

**NATIONAL PRODUCTS**

C-133, MAYAPURI INDUSTRIAL AREA, PHASE-2, MAYAPURI,  
NEW DELHI-110064

Has been assessed by SCPL and found to comply with the requirements of

### ISO 14001:2015

The Environmental Management System

**Certification Scope:**

Manufacturing of Fluxes, Solvents and Subsequently Added Solder Stick/Ingot, Solder Wire, Solder Paste and Environment Friendly Lead Free Solder & Paste

**Certification Calendar**

UI Number: SCPL1219E253  
Certificate Number: IAS0512E1177  
Date of Registration: 05-Dec-2019  
Date of Issue: 05-Dec-2019

**1<sup>st</sup> Surveillance on/before:** 04-Nov-2020  
**2<sup>nd</sup> Surveillance on/before:** 04-Nov-2021  
**Date of Expiry:** 04-Dec-2022






**SAGACI CERTIFICATIONS PVT. LTD.**

This certificate has been issued by Sagaci Certifications Pvt. Ltd., 20, A-2, Shree Arcade, Acharya Nivaran, Mayapuri Vihar Phase - I, Delhi - 110091, India and will remain current subject to the company maintaining its system to the required standard(s). This will be monitored regularly by SCPL. The use of the IAS accreditation Mark indicates Accreditation in respect of those activities covered by the Accreditation Certificate. Further clarification regarding the scope of this certificate and the applicability of the standard requirements may be obtained by: Phone: 011-43601911 Mob: +91 9560472730, Email: info@sagacert.com, Web: www.sagacert.com



## Certificate of Registration

This is to certify that

**National Products**

C- 133, Mayapuri Industrial Area, Phase - II, New Delhi - 110064 India.

has been assessed by RICL and found to comply with the requirements of

### ISO 9001 : 2015

#### Quality Management System

For the following activities:

**Manufacture & Supply of Soldering Material (Solder Stick, Solder Wire, Solder Paste, Soldering Fluxes).**

This Certificate is Valid from 07/08/2019 Until 02/08/2020

Date of Initial Certification: 03/08/2018  
1<sup>st</sup> Surveillance Successfully Conducted and Surveillance on or before: 02/07/2020  
Certificate Valid Until: 02/08/2021  
IAF is a full member of International Accreditation Forum (IAF)




**United Accreditation Foundation**  
3510, Colmar, Norfolk, VA 23509,  
United States of America.

**Director**  
**Royal Impact Certification Ltd.**  
623, Tower-B, IThum, Plot No. A-40, Sector - 62, Noida 201301, India.  
www.isointernational.org, info@isointernational.org  
Phone: +91 120-4113303, 9701618786  
This Certificate can be verified at: www.isointernational.org

IAF is a full member of International Accreditation Forum (IAF), the membership status can be verified at www.iaf.nu. Certificate remains the property of Royal Impact Certification Limited. Must be returned on request or if certificate is withdrawn. Validity of this certificate is subject to successful surveillance audits as per dates given above.



ULR - TC64421900007035F TEST REPORT

Report No. : **MAN:TR:1053007192** DATE : 18/04/2019



National Products  
C-133, MAYAPURI INDL AREA, PHASE-2, MAYAPURI  
New Delhi-110064  
IN  
CONTACT PERSON : MR.MOHAMMAD ZUBAIR

THE FOLLOWING SAMPLE(S) WAS/WERE SUBMITTED AND IDENTIFIED BY/ON BEHALF OF THE CUSTOMER AS :

SAMPLE DESCRIPTION	ROHS SOLDER
COUNTRY OF ORIGIN	INDIA
SAMPLE RECD ON	11/04/2019
TEST(S) REQUESTED	ROHS TEST

TESTING PERIOD : 12/04/2019 - 18/04/2019

**Conclusion :** Based on the performed tests on submitted sample(s), the results of Cadmium, Lead, Mercury, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU (Pass for testing on submitted sample)

Per Pro SGS India Private Ltd



Authorized Signatory  
Durgesh Pandey  
(Sr.Executive)  
Email your Test Report Related Enquiries at Feedback.trp@sgs.com



# Our Range of Products

<b>Metals and Alloys</b>
<b>Lead- Free Solder Stick And Wire</b>
<b>Leaded Solder Stick And Wire</b>
<b>Solder Wire (Solid ,No Clean ,RMA ,Water Soluble And Urea-Base)</b>
<b>Aluminum Solder</b>
<b>Tin/Zinc Wire</b>
<b>Tin &amp;Solder Anodes</b>

<b>Flux and Soldering Chemicals</b>
<b>Lead Free Fluxes</b>
<b>V.O.C Free Fluxes</b>
<b>Hot Air Leveling Fluxes</b>
<b>No Clean Fluxes</b>
<b>Water Soluble Fluxes</b>
<b>Tinning Fluxes</b>
<b>Aluminum Fluxes</b>
<b>BGA Flux</b>

<b>Solder Paste</b>
<b>Leaded Solder Paste</b>
<b>Lead – Free Solder Paste</b>

<b>Solvents and PCB Chemicals</b>
<b>Ultra Cleaners</b>
<b>Anti-oxidants(Powder)</b>
<b>Heat Sink Compound</b>

## NP FLUXES AND SOLVENTS SELECTION GUIDE CHART:-

<b>Product Designation</b>	<b>Technology</b>	<b>Color</b>	<b>Solid content</b>	<b>Specific Gravity</b>	<b>RECOMMENDED APPLICATION</b>
<b>NP- 215</b>	<b>Rosin - Based</b>	<b>Clear amber</b>	<b>12-14%</b>	<b>0.825</b>	<b>Flux has excellent foaming properties and can be applied on printed circuit boards by foam, brushing or spraying. Applicable through hole and discrete components. Density should be maintained using '510' solvent.</b>
<b>NP-207</b>	<b>Rosin - Based</b>	<b>Clear amber</b>	<b>6 – 8%</b>	<b>0.805</b>	<b>Flux can be applied on component or printed circuit boards by dipping, brushing or spraying. Flux density should be maintained using '505' solvent</b>
<b>NP 302 - series</b>	<b>No Clean Halide free</b>	<b>Colorless</b>	<b>2 - 3%</b>	<b>0.8</b>	<b>Surface mount devices and high density plated through hole assembly soldering for electronics mother board, telecommunication applications. Used for Both spray and foam. Flux density should be maintained using '505' solvent.</b>
<b>NP 306</b>	<b>Resin based No clean</b>	<b>Pale yellow</b>	<b>4-5%</b>	<b>0.805</b>	<b>Wave soldering, leaves a low level of non-tacky, non-corrosive residue. Flux density should be maintained using '505' solvent.</b>
<b>NP- 800 series</b>	<b>Rosin – Containing No Clean Halide Free</b>	<b>Pale yellow</b>	<b>4 – 5%</b>	<b>0.795-0.805</b>	<b>Wave soldering, leaves a low level of non-tacky, non-corrosive residue. Flux density should be maintained using '505' solvent.</b>
<b>Solder Paste Flux</b>	<b>Rosin</b>	<b>Pale yellow</b>	<b>Semi solid</b>	<b>High viscosity</b>	<b>For soldering of brass, bronze, copper, nickel heavy components</b>
<b>BGA –Flux</b>	<b>No clean</b>	<b>Pale yellow</b>	<b>Semi solid</b>	<b>High viscosity</b>	<b>Applicable for BGA ,flip chip component and SMD rework</b>

<b>NP- 900</b>	<b>VOC – Free</b>	<b>Colorless</b>	<b>2.50%</b>	<b>1.01- 1.05</b>	<b>Flux can be applied on printed circuit boards by foam, brushing or spraying. Non Tacky bright solder joints.</b>
<b>NP – Tinning Flux</b>	<b>Water based</b>	<b>Colorless</b>	<b>15–20 %</b>	<b>1.05- 1.10</b>	<b>The flux can be applied on pre-cleaned PCBs by dip, roller-coating to brush.</b>
<b>NP – Hot Air leveling Flux</b>	<b>Water soluble</b>	<b>Light pink</b>	<b>--</b>	<b>1.10- 1.15</b>	<b>The flux can be applied on pre-cleaned PCBs by dip, roller-coating to brush. The flux has good thermal stability for use at solder bath temperature up to 260°C. After solder coating the flux residues are completely soluble in water; thus providing PCB,s with high ionic cleanliness</b>
<b>NP – Aluminum flux</b>	<b>Water soluble</b>	<b>Amber to brown</b>	<b>--</b>	<b>1.35</b>	<b>Suitable for soldering of aluminum to aluminum, aluminum to copper, aluminum to brass and aluminum to plated terminals. NP-Aluminum Flux can be used with all conventional soldering techniques.</b>

## Solvents

<b>NP- 505,510 Solvent/thinner</b>	<b>Solvent based</b>	<b>Colorless</b>	<b>---</b>	<b>0.785</b>	<b>To maintain the specified density of the flux - Flux NP 302, 306, 800-series</b>
<b>NP- 600 Ultra cleaner</b>	<b>Solvent based</b>	<b>Colorless</b>	<b>--</b>	<b>0.88</b>	<b>Post Solder PCB Cleaning</b>
<b>NP 640</b>	<b>Solvent based</b>	<b>Colorless</b>	<b>--</b>	<b>0.785</b>	<b>Post Solder PCB Cleaning</b>

# High Performance Solders

- **Solder Bars** - high purity excellent solder ability Good wetting low oxides, low dross
- **Solder Anodes** – ultra pure composition, bright Appearance, excellent wetting, any size
- **Solder Wires** – Very low level fumes ,clear non – tacky residue, In RMA /No clean technology

## Lead Free solders

NP makes Lead free Solders have complied with all the requirements of RoHS directives. It has higher mechanical strength, higher yield, higher reliability, and excellent wetting.

- Wave and Dip lead-free solders are available in a choice of lead-free variants, **96.5Sn/3.5Ag**, **96.5Sn/3.0Ag/0.5Cu**, **99Sn/0.3Ag/0.7Cu** and **99.3 Sn/0.7Cu**

**“Other Solder Alloys Are Available  
Upon Our Customers Request.”**

# SOLDER PASTE

<b>PRODUCT DESIGNATION</b>	<b>NP 109</b>	<b>NP 110</b>
Alloy Composition	63Sn37Pb	62Sn36Pb2Ag
Metal %, by weight	89.50%	88 – 91 %
Powder size	Type #3	Type #3
Activity level	R0L0	R0L0
Halide content	Halide free	Halide free
Copper Mirror Corrosion Test	Pass	Pass
Solder Ball	Pass	Pass
Flux classification	No - clean	No - clean



# Contact Details

## EMAIL ID

**SKG@NPSOLDERS.COM, NATIONALPRODUCTS133@GMAIL.COM**

## WEBSITE

**WWW.NPSOLDERS.COM**

## CONTACT US AT

**91-11-28115079; 28115153, 7982704481**

## HEAD OFFICE

**C-133, Mayapuri Industrial Area Phase II, New Delhi, Delhi 110064**

## MANUFACTURING UNIT

**A-138,EPIP, Neemrana, Rajasthan 301709**